IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

Christophe Pierrat et al.

Application No.:

Filed Herewith

Parent Appln. Group No.: 2825

Filed:

10/16/2003

Parent Appln. Examiner: Paul Dinh

For: "Displacing Edge Segments On A Fabrication Layout Based On Proximity Effects Model Amplitudes For

Correcting Proximity Effects"

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Date: October 16, 2003

INFORMATION DISCLOSURE STATEMENT

List of Sections Forming Part of This Information Disclosure Statement

The following sections are being submitted for this Information Disclosure Statement:

1. Identification of Prior Application in Which Listed Information Was Already Cited and for Which No Copies Are Submitted or Need Be Submitted

Section 1. Identification of Prior Application in Which Listed Information Was Already Cited and for Which No Copies Are Submitted or Need Be Submitted

This application relies, under 35 U.S.C. § 120, on the earlier filing date of prior application Serial No.: 09/728,885, filed on December 1, 2000, now allowed (U.S. Patent Number not yet known).

Copies of the documents listed on the accompanying Form PTO-1449 (22 pages) that are not enclosed were previously submitted in Application No. 09/728,885, from which this Application claims an earlier effective filing date.

Applicants respectfully request that the listed information be considered by the Examiner and be made of record in the above-identified application. If form PTO-1449 is enclosed, the Examiner is requested to initial and return it in accordance with MPEP § 609.

This statement is not intended to represent that a search has been made or that the information cited in the statement is, or is considered to be, material to patentability as defined in 37 C.F.R. § 1.56.

\boxtimes	This sta	tement	qualifies under 37 C.F.R. § 1.97, subsection (b) because (check all that apply):
	\boxtimes	(1)	It is being filed within 3 months of the application filing date and is other than a continued prosecution application under § 1.53(d) OR
		(2)	It is being filed within 3 months of entry of a national stage
		(3)	It is being filed before the mail date of the first Office Action on the merits.
		(4)	It is being filed before the mailing of a first Office Action after the filing of a request for continued examination under § 1 114

Atty. Dkt. No.: NTI-019-5-1D

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	mailing	R. § 1.97(c). If this statement is being filed after the period specified in § 1.97(b), but before the date of the earlier of a final office action under § 1.113, a notice of allowance under § 1.311, or an anat otherwise closes prosecution in the application, then:
		a certification as specified in § 1.97(e) is provided below; or
		a fee of \$180.00 as set forth in § 1.17(p) is authorized below, enclosed, or included with the payment of other papers filed together with this statement.
		R. § $1.97(d)$. If this statement is being filed after the period specified in § $1.97(c)$, but on or before t of the issue fee, then:
	A.	a certification as specified in § 1.97(e) is completed below; and
•	B.	a fee of \$180.00 as set forth in § 1.17(p) is authorized below, enclosed, or included with the payment of other papers filed together with this statement.
\boxtimes		horization. Applicant believes NO fee is due. However, in the event a fee is found to be due, the ssioner is hereby authorized to charge Deposit Account No. 50-0574 (Docket No. NTI-019-5-1D).
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Date:	10-	6-03 Signature of Practitioner
	o.: 1-408 ner No.:	Jeanette S. Harms, Reg. No. 35,537 Bever, Hoffman & Harms, LLP 29477
Service a Patent A 1450.	as EXPRE	at this correspondence is being deposited with the United States Postal SS MAIL, Label No: EV 338 032 709 US addressed to: Mail Stop, Commissioner for Patents, P.O. Box 1450, Alexandria, VA, 22313-
Date	<u> </u>	Signature: Rebecca A. Baumann

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